NOTES: unless otherwise specified

1.0 Applicable documents:
The following items are required:

- PATTERN PLAN
- WNSN-EL-04-1002
- DETAIL DRAWING
- WNSN-EL-04-1002 THIS DOCUMENT

2.0 BASE MATERIAL:

2.1 Laminated base material shall be natural color, FR-4 or equivalent.
See Detail A-A for layer-to-layer specification and total thickness.

2.2 O-ring shall be selected at vendor discretion to meet over
total thickness and end item requirements.

3.0 COPPER PLATING:

3.1 Copper plating shall have a minimum purity of .995 percent and a maximum
thickness of .001 inch. This also applies to the plating in the holes.

4.0 SOLDERMASK:

4.1 Apply LSR Green soldermask over bore copper according to the soldermask
pattern file per PCL-01384.

5.0 FINISH:

5.1 SWIRL: all exposed metal shall be coated in molten solder and hot air leveled.

5.6 SILK SCREEN:

5.6.1 Silk screen top (‘+’ side) and bottom (‘−’ side) side of board using white epoxy ink
according to the −15 pattern file and the −165 pattern file.

5.7 DIMENSIONS:

5.7.1 All dimensions are in inches.

5.8 TOLERANCES:

5.8.1 O-rings tolerance ± .003 after plating unless otherwise specified.
5.8.2 Centerline width and spacing shall be ±0.05 of the artwork original.
5.8.3 Layer to layer registration shall be ±0.005 inches of true position.
5.8.4 Board dimensions shall meet the requirements of the board drawing.
5.8.5 Warp and twist shall not exceed ±0.005 as defined in PC-A-698.

5.9 APPEARANCE:

5.9.1 All inside and outside corners shall have a maximum radius of .005
5.9.2 Remove all burrs and smooth sharp edges to .018 max.

VENDOR NOTE: NOTIFY US OF ANY CONFLICTING REQUIREMENTS OR IF BOARDS CANNOT
BE MANUFACTURED TO MEET THE ABOVE REQUIREMENTS, DUE TO VENDORS PROCESS
AND/OR TECHNIQUES OR BECAUSE PHOTO TOOLS AND/OR SPECIFICATIONS ARE INADEQUATE.